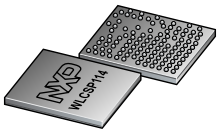
SOT2235-1

WLCSP114, wafer level chip scale package, 114 terminals, 0.33 mm pitch, 4.495 mm x 4.0 mm x 0.455 mm body (backside coating included)

3 December 2024 Package information



1 Package summary

Terminal position code	U (upper)
Package type descriptive code	WLCSP114
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	S (silicon)
Mounting method type	S (surface mount)
Issue date	02-12-2024
Manufacturer package code	98ASA02158D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.465	4.495	4.525	mm
package width	3.97	4	4.03	mm
seated height	0.3	0.325	0.35	mm
package height	0.425	0.455	0.485	mm
nominal pitch	-	0.33	-	mm
actual quantity of termination	-	114	-	

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2 Package outline

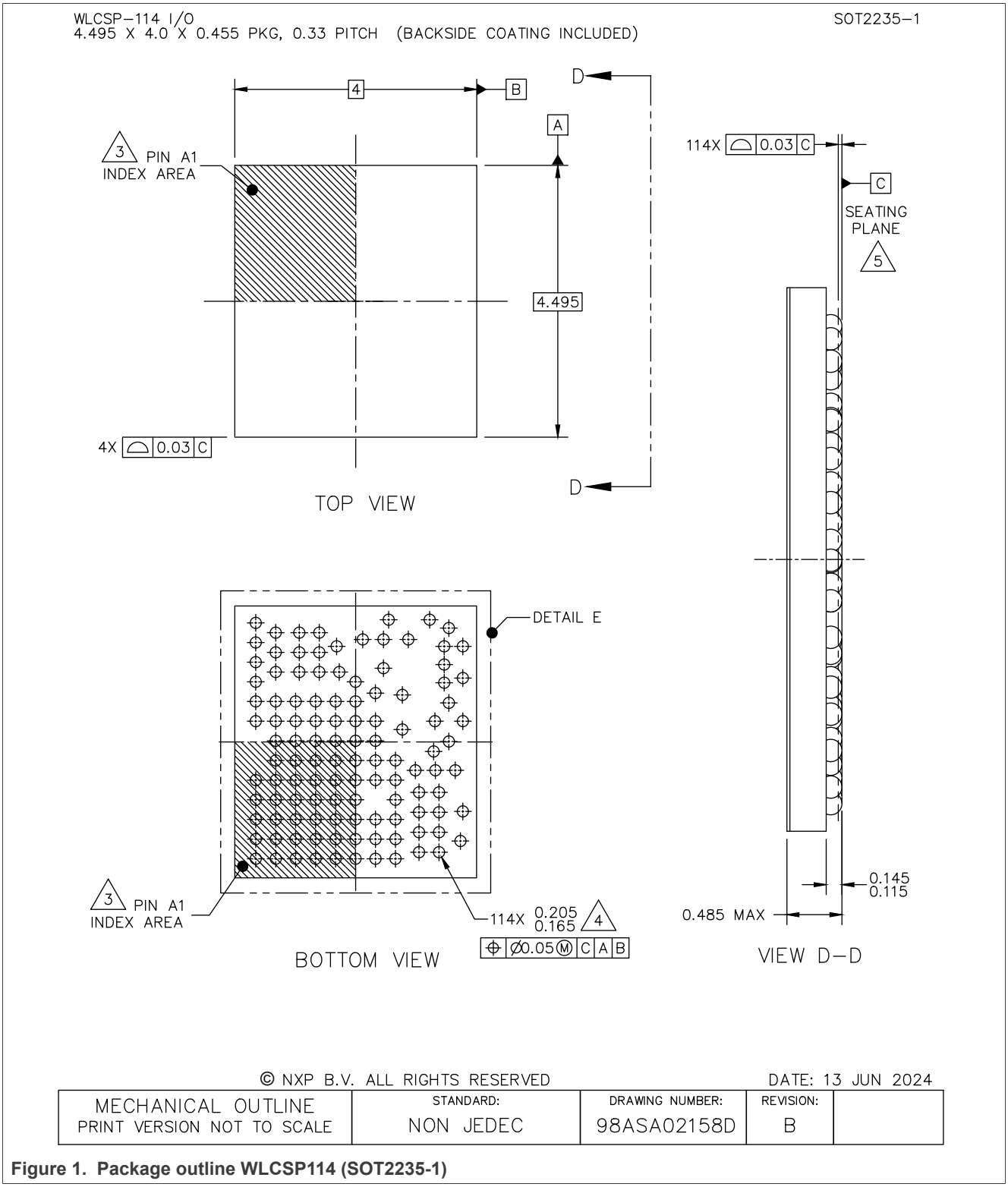


Figure 1. Package outline WLCSP114 (SOT2235-1)

WLCSP114, wafer level chip scale package, 114 terminals, 0.33 mm pitch, 4.495 mm x 4.0 mm x 0.455 mm body (backside coating included)

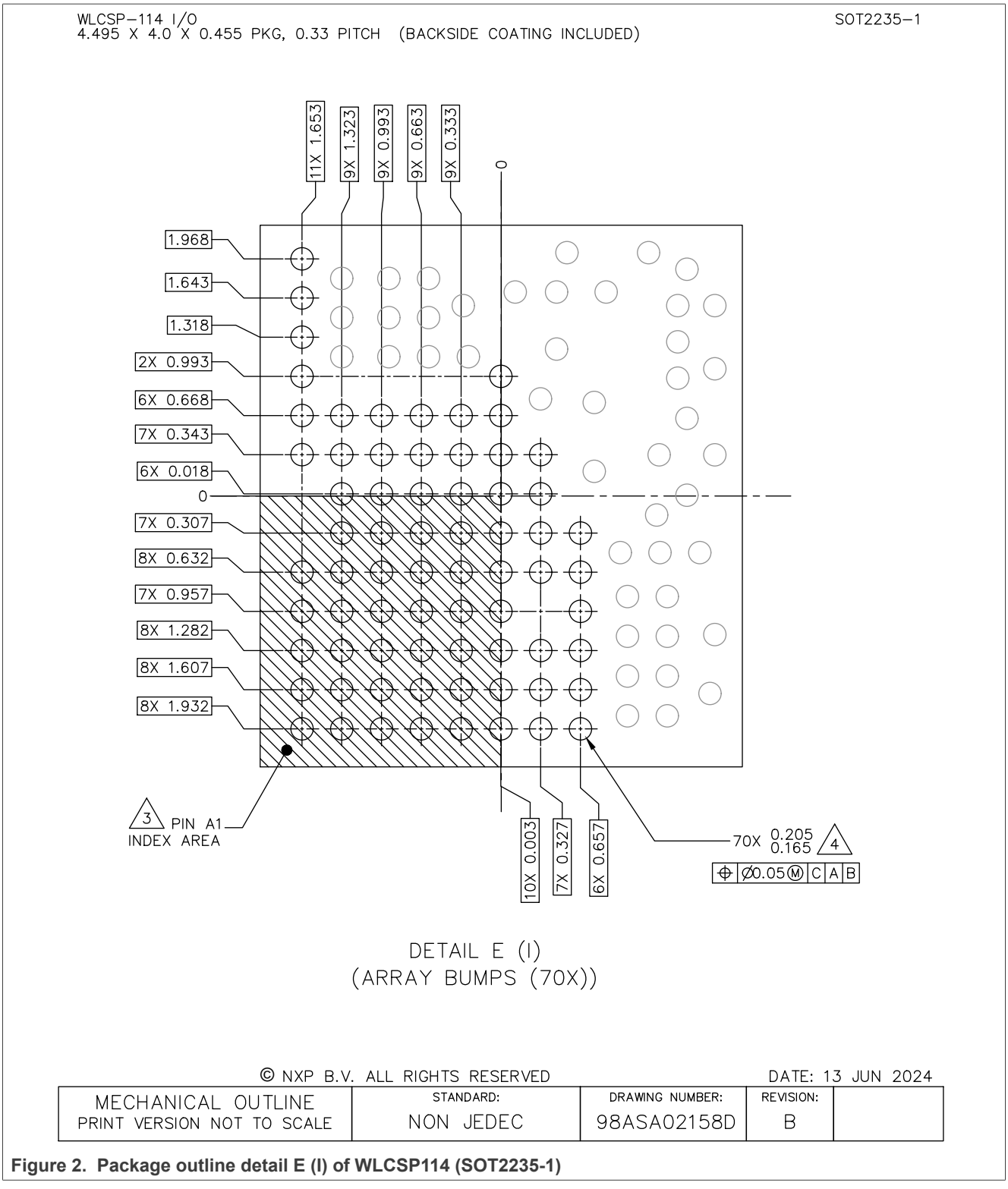


Figure 2. Package outline detail E (I) of WLCSP114 (SOT2235-1)

WLCSP114, wafer level chip scale package, 114 terminals, 0.33 mm pitch, 4.495 mm x 4.0 mm x 0.455 mm body (backside coating included)

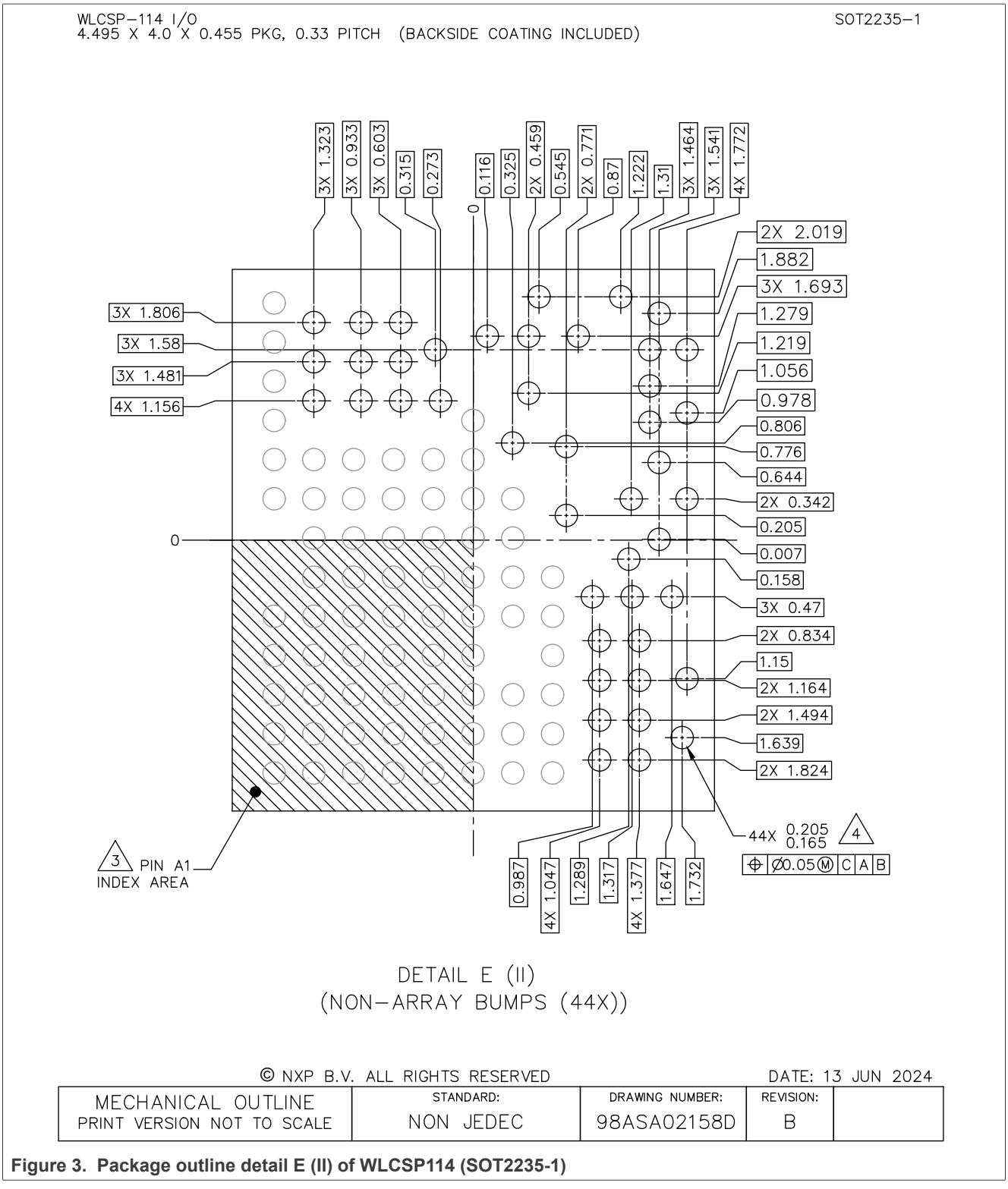


Figure 3. Package outline detail E (II) of WLCSP114 (SOT2235-1)

3 Soldering

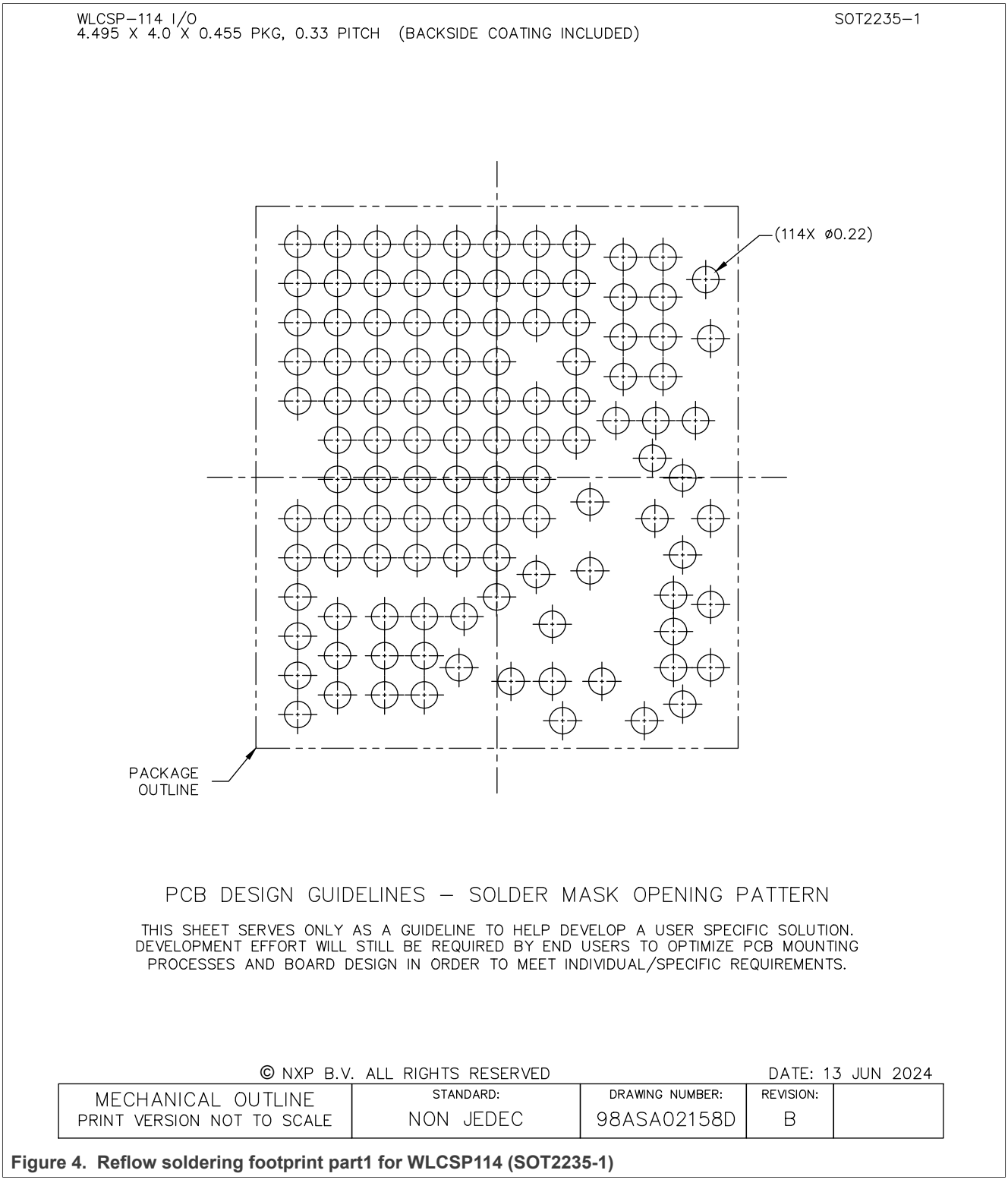


Figure 4. Reflow soldering footprint part1 for WLCSP114 (SOT2235-1)

WLCSP114, wafer level chip scale package, 114 terminals, 0.33 mm pitch, 4.495 mm x 4.0 mm x 0.455 mm body (backside coating included)

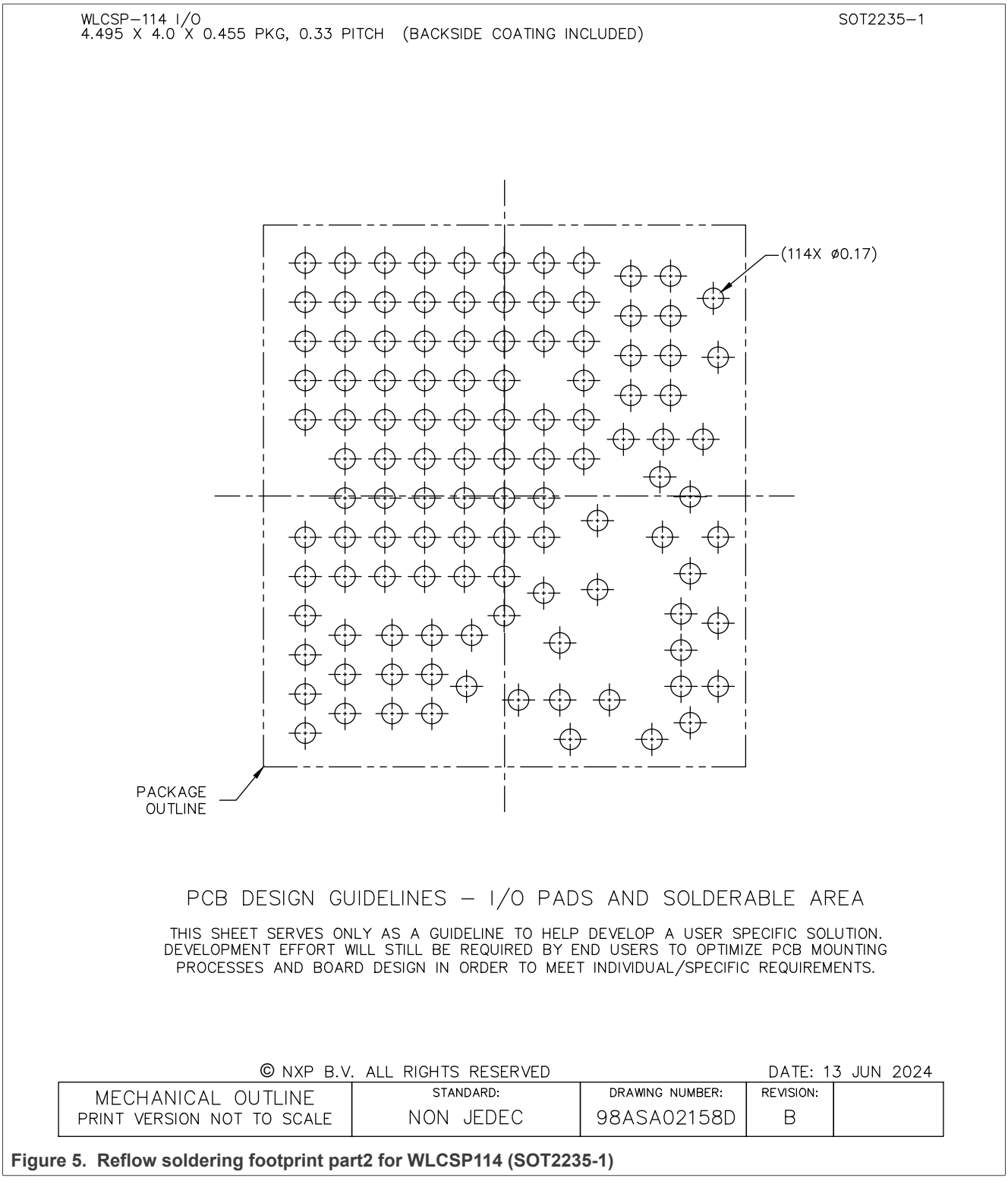


Figure 5. Reflow soldering footprint part2 for WLCSP114 (SOT2235-1)

WLCSP114, wafer level chip scale package, 114 terminals, 0.33 mm pitch, 4.495 mm x 4.0 mm x 0.455 mm body (backside coating included)

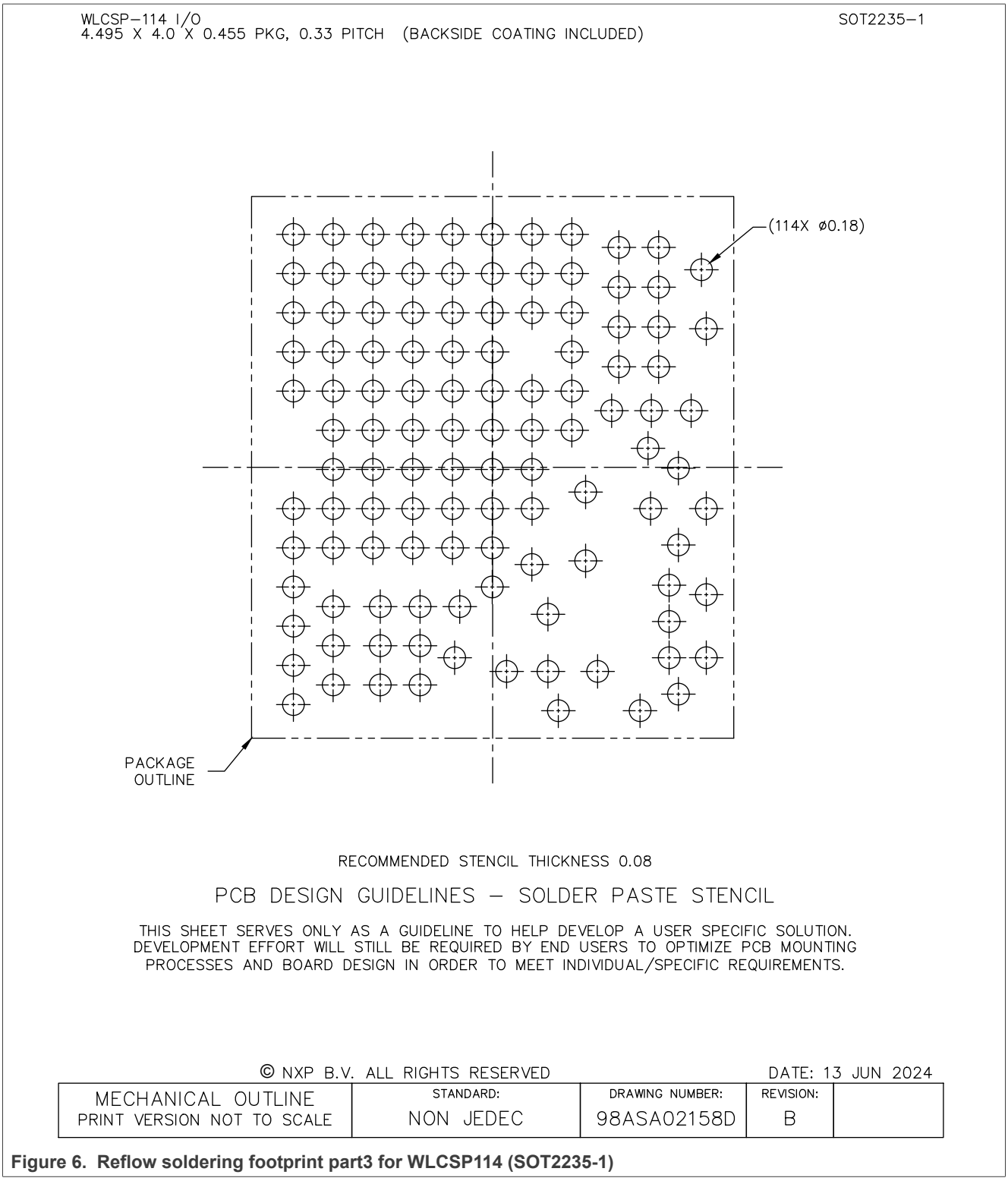
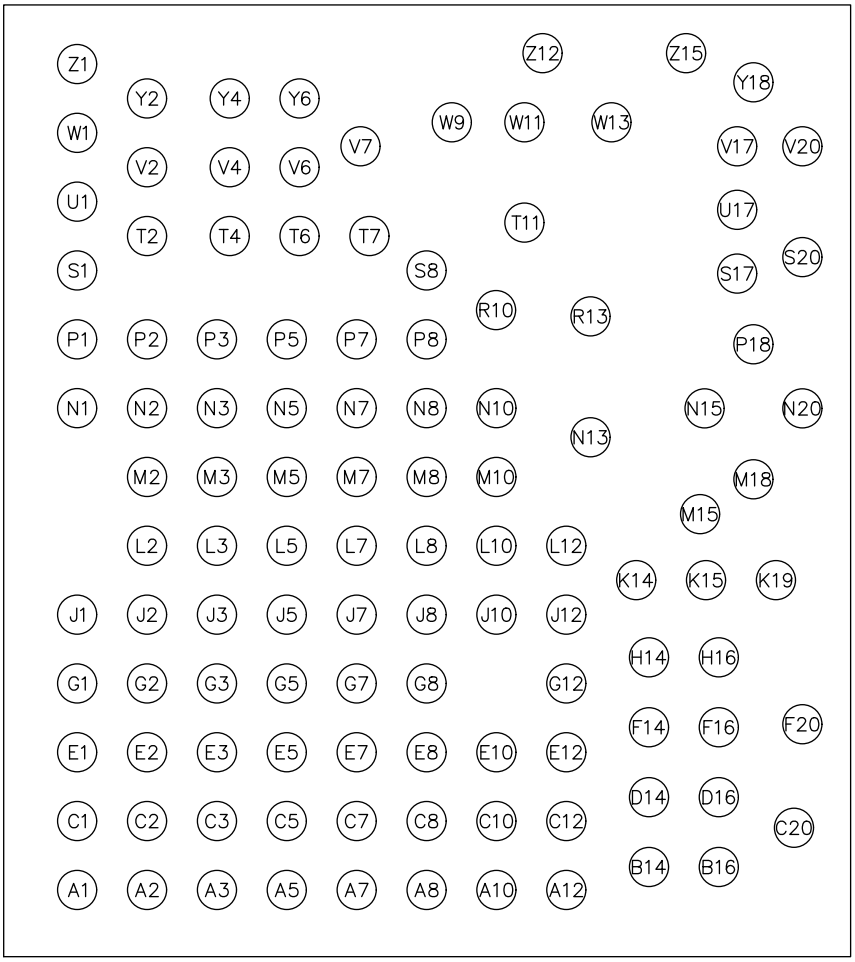


Figure 6. Reflow soldering footprint part3 for WLCSP114 (SOT2235-1)

WLCSP114, wafer level chip scale package, 114 terminals, 0.33 mm pitch, 4.495 mm x 4.0 mm x 0.455 mm body (backside coating included)

WLCSP−114 I/O
4.495 X 4.0 X 0.455 PKG, 0.33 PITCH (BACKSIDE COATING INCLUDED)

SOT2235−1



PIN NUMBERS
(VIEWED FROM BOTTOM, SAME AS DETAIL E)

DATE: 13 JUN 2024

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA02158D	REVISION: B	

Figure 7. Reflow soldering footprint part4 for WLCSP114 (SOT2235-1)

WLCSP114, wafer level chip scale package, 114 terminals, 0.33 mm pitch, 4.495 mm x 4.0 mm x 0.455 mm body (backside coating included)

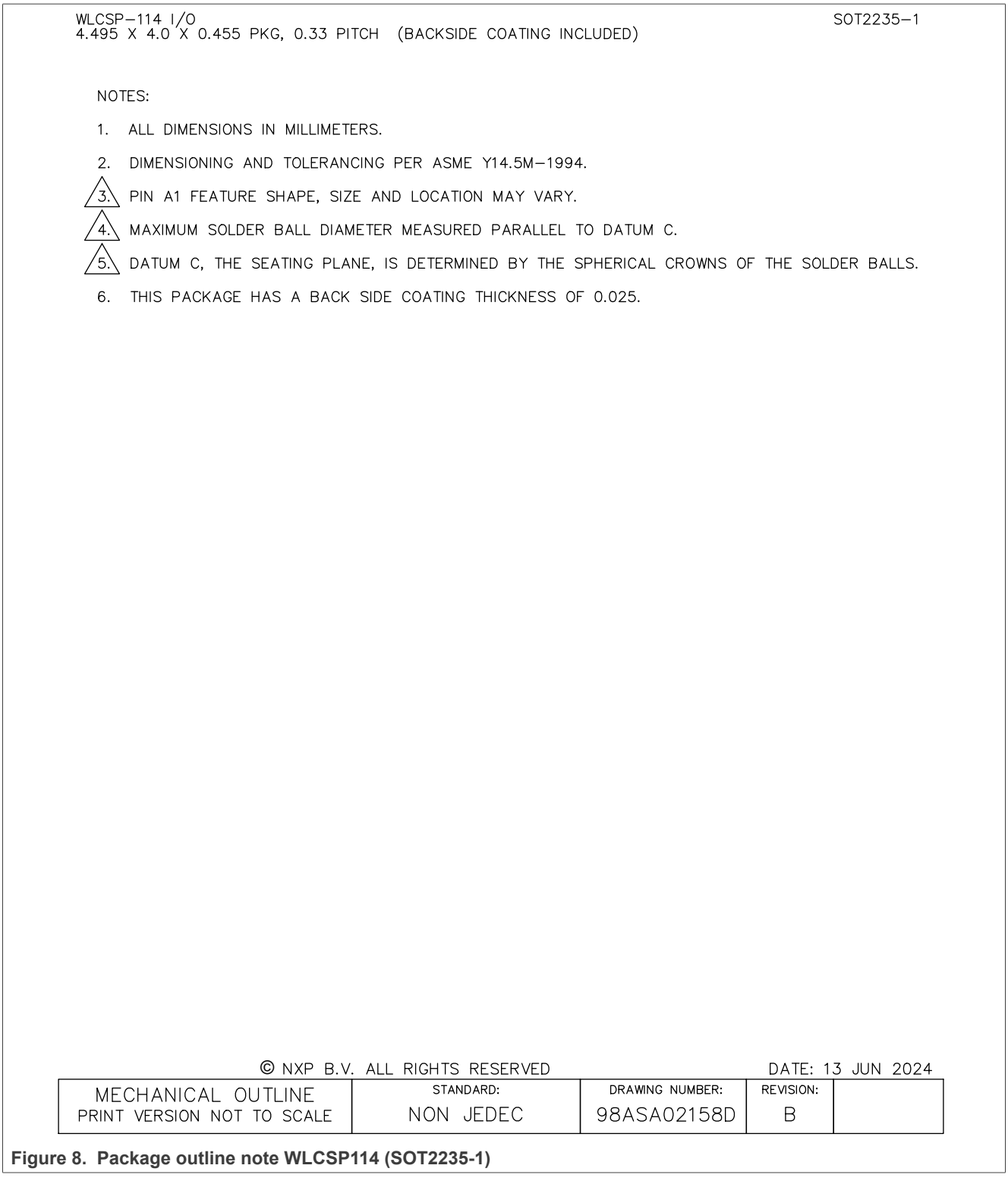


Figure 8. Package outline note WLCSP114 (SOT2235-1)

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